

# BZT52C2V4S THRU BZT52C39S

## SOD323 Plastic-Encapsulate Diodes

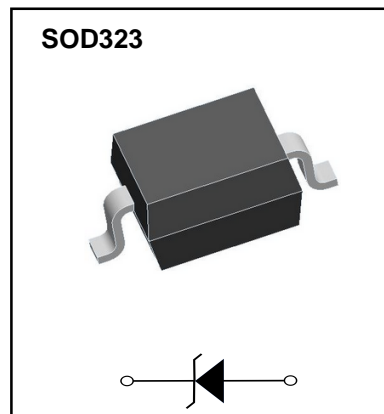
### Zener Diodes

#### Features

- $P_d$  200mW
- $V_z$  2.4V- 39V

#### Applications

- Stabilizing Voltage



#### Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions	Max
Power dissipation	$P_d$	mW	$T_A=25^\circ\text{C}$	200
Zener current	$I_z$	mA		20
Maximum junction temperature	$T_j$	$^\circ\text{C}$		150
Storage temperature range	$T_{stg}$	$^\circ\text{C}$		-65 to +150

#### Electrical Characteristics ( $T_A=25^\circ\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Conditions	Max
Thermal resistance	$R_{\theta JA}$	$^\circ\text{C}/\text{W}$	Between junction and ambient	625
Forward voltage	$V_F$	V	$I_F = 10\text{mA}$	0.9

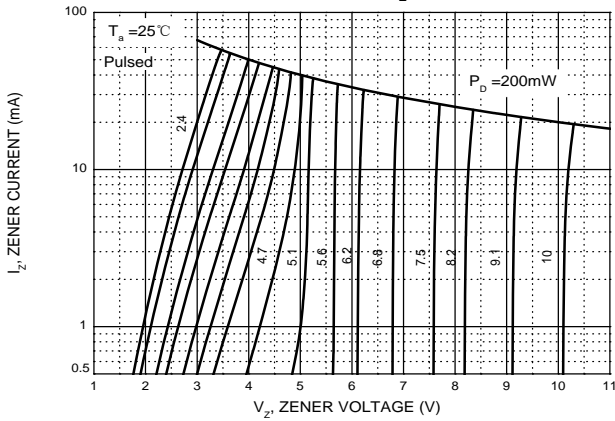
## Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

TYPE	Marking	Zener Voltage Range (Note 2)				Maximum Zener Impedance (Note 3)			Maximum Reverse Current (Note 2)		Typical Temperature Coefficient @ $I_{ZTC}$ mV/°C		Test Current $I_{ZTC}$
		$V_Z@I_{ZT}$			$I_{ZT}$	$Z_{ZT}@I_{ZT}$	$Z_{ZK}@I_{ZK}$	$I_{ZK}$	$I_R$	$V_R$	Min	Max	mA
		Nom(V)	Min(V)	Max(V)	(mA)	$\Omega$	(mA)	$\mu\text{A}$	V				
BZT52C2V4S	WX	2.4	2.20	2.60	5	100	600	1.0	50	1.0	-3.5	0	5
BZT52C2V7S	W1	2.7	2.5	2.9	5	100	600	1.0	20	1.0	-3.5	0	5
BZT52C3V0S	W2	3.0	2.8	3.2	5	95	600	1.0	10	1.0	-3.5	0	5
BZT52C3V3S	W3	3.3	3.1	3.5	5	95	600	1.0	5	1.0	-3.5	0	5
BZT52C3V6S	W4	3.6	3.4	3.8	5	90	600	1.0	5	1.0	-3.5	0	5
BZT52C3V9S	W5	3.9	3.7	4.1	5	90	600	1.0	3	1.0	-3.5	0	5
BZT52C4V3S	W6	4.3	4.0	4.6	5	90	600	1.0	3	1.0	-3.5	0	5
BZT52C4V7S	W7	4.7	4.4	5.0	5	80	500	1.0	3	2.0	-3.5	0.2	5
BZT52C5V1S	W8	5.1	4.8	5.4	5	60	480	1.0	2	2.0	-2.7	1.2	5
BZT52C5V6S	W9	5.6	5.2	6.0	5	40	400	1.0	1	2.0	-2	2.5	5
BZT52C6V2S	WA	6.2	5.8	6.6	5	10	150	1.0	3	4.0	0.4	3.7	5
BZT52C6V8S	WB	6.8	6.4	7.2	5	15	80	1.0	2	4.0	1.2	4.5	5
BZT52C7V5S	WC	7.5	7.0	7.9	5	15	80	1.0	1	5.0	2.5	5.3	5
BZT52C8V2S	WD	8.2	7.7	8.7	5	15	80	1.0	0.7	5.0	3.2	6.2	5
BZT52C9V1S	WE	9.1	8.5	9.6	5	15	100	1.0	0.5	6.0	3.8	7.0	5
BZT52C10S	WF	10	9.4	10.6	5	20	150	1.0	0.2	7.0	4.5	8.0	5
BZT52C11S	WG	11	10.4	11.6	5	20	150	1.0	0.1	8.0	5.4	9.0	5
BZT52C12S	WH	12	11.4	12.7	5	25	150	1.0	0.1	8.0	6.0	10.0	5
BZT52C13S	WI	13	12.4	14.1	5	30	170	1.0	0.1	8.0	7.0	11.0	5
BZT52C15S	WJ	15	13.8	15.6	5	30	200	1.0	0.1	10.5	9.2	13	5
BZT52C16S	WK	16	15.3	17.1	5	40	200	1.0	0.1	11.2	10.4	14	5
BZT52C18S	WL	18	16.8	19.1	5	45	225	1.0	0.1	12.6	12.4	16	5
BZT52C20S	WM	20	18.8	21.2	5	55	225	1.0	0.1	14.0	14.4	18.0	5
BZT52C22S	WN	22	20.8	23.3	5	55	250	1.0	0.1	15.4	16.4	20.0	5
BZT52C24S	WO	24	22.8	25.6	5	70	250	1.0	0.1	16.8	18.4	22.0	5
BZT52C27S	WP	27	25.1	28.9	2	80	300	0.5	0.1	18.9	21.4	25.3	2
BZT52C30S	WQ	30	28.0	32.0	2	80	300	0.5	0.1	21.0	24.4	29.4	2
BZT52C33S	WR	33	31.0	35.0	2	80	325	0.5	0.1	23.1	27.4	33.4	2
BZT52C36S	WS	36	34.0	38.0	2	90	350	0.5	0.1	25.2	30.4	37.4	2
BZT52C39S	WT	39	37.0	41.0	2	130	350	0.5	0.1	27.3	33.4	41.2	2

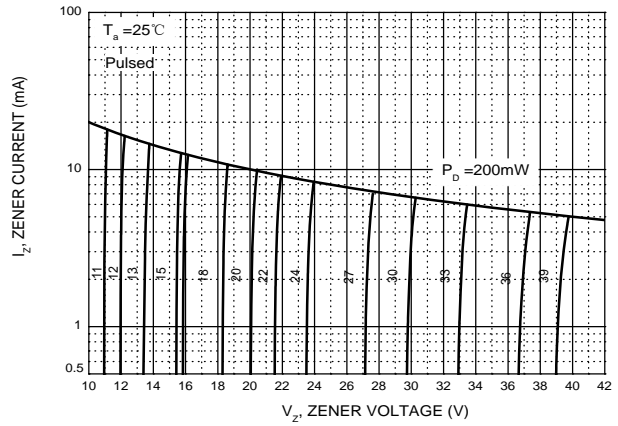
- Notes: 1. Device mounted on ceramic PCBK7.6mm x 9.4mm x 0.87mm with pad areas 25mm<sup>2</sup>.  
 2. Short duration test pulse used to minimize self-heating effect.  
 3. f = 1kHz.

# Typical Characteristics

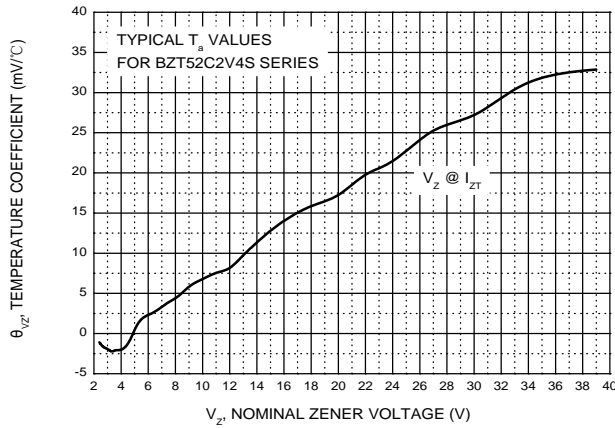
Zener Characteristics ( $V_z$  Up to 10 V)



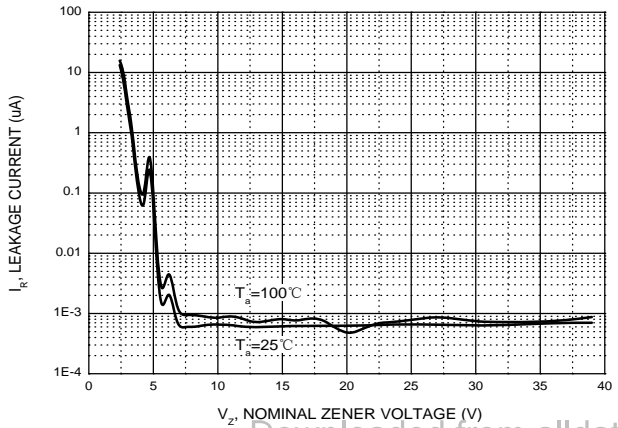
Zener Characteristics (11 V to 39 V)



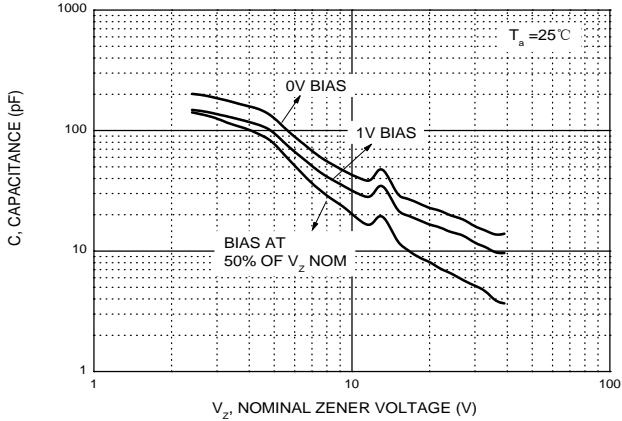
Temperature Coefficients



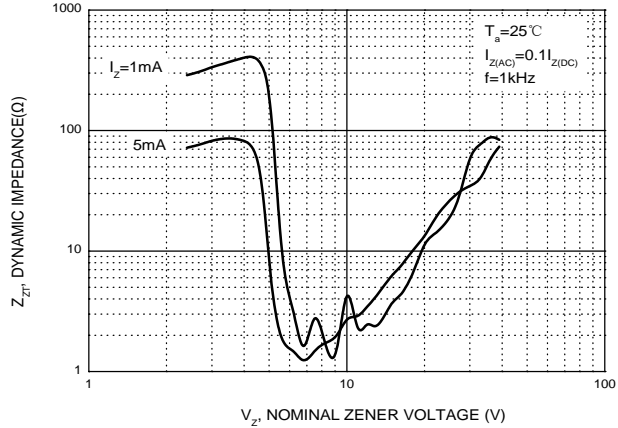
Typical Leakage Current



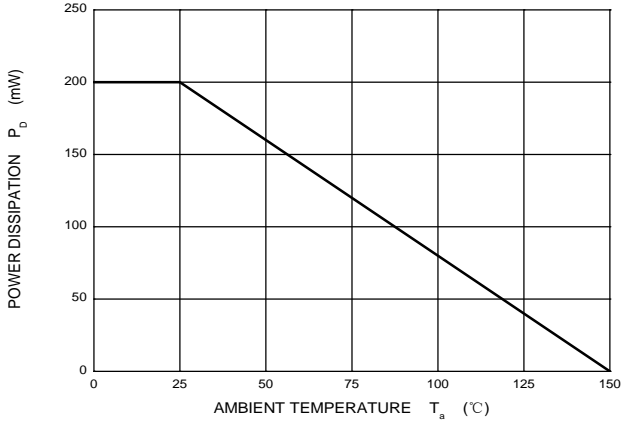
Typical Capacitance



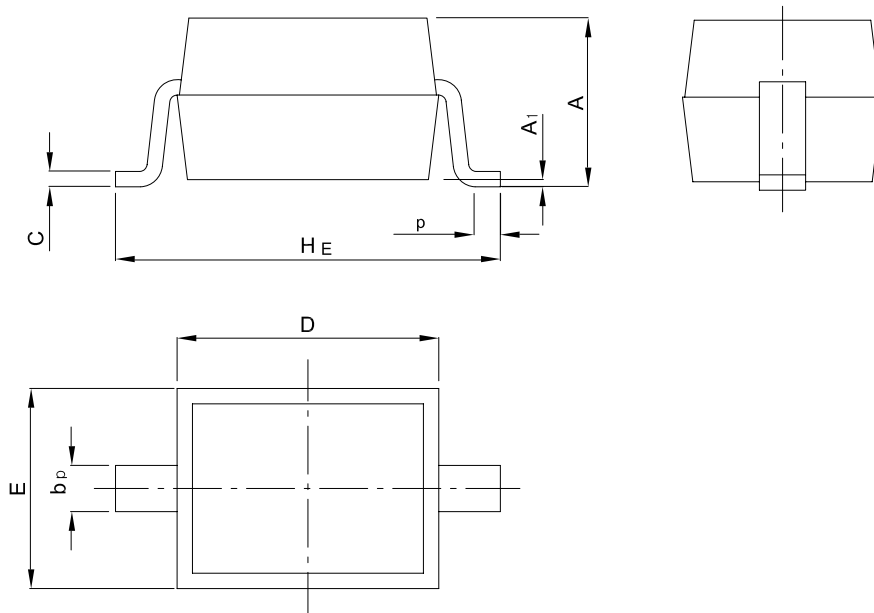
Effect of Zener Voltage on Zener Impedance



Power Derating Curve



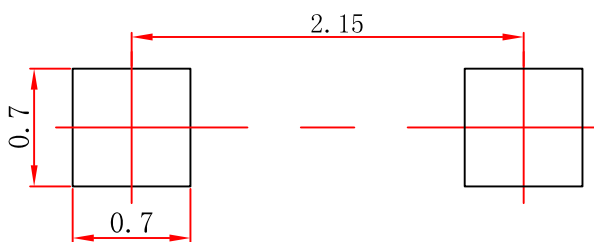
## SOD323 Package Outline Dimensions



UNIT	A	bp	C	D	E	HE	A1	Lp
mm	1.20	0.40	0.15	1.80	1.35	2.80	0.10	0.50
	0.90	0.25	0.10	1.60	1.15	2.30	0.01	0.20

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## SOD323 Suggested Pad Layout



### Note:

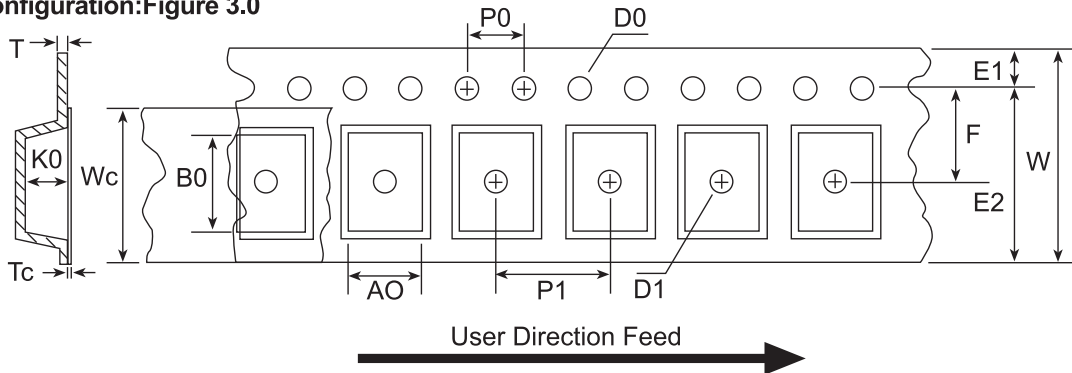
1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05$  mm.
3. The pad layout is for reference purposes only.

### NOTICE

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# Reel Taping Specifications For Surface Mount Devices-SOD323

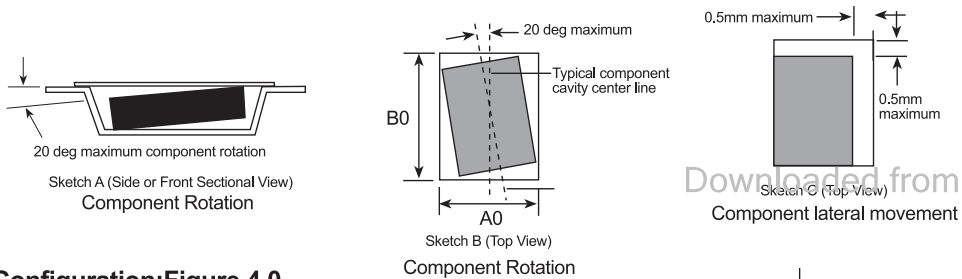
## SOD323 Embossed Carrier Tape Configuration: Figure 3.0



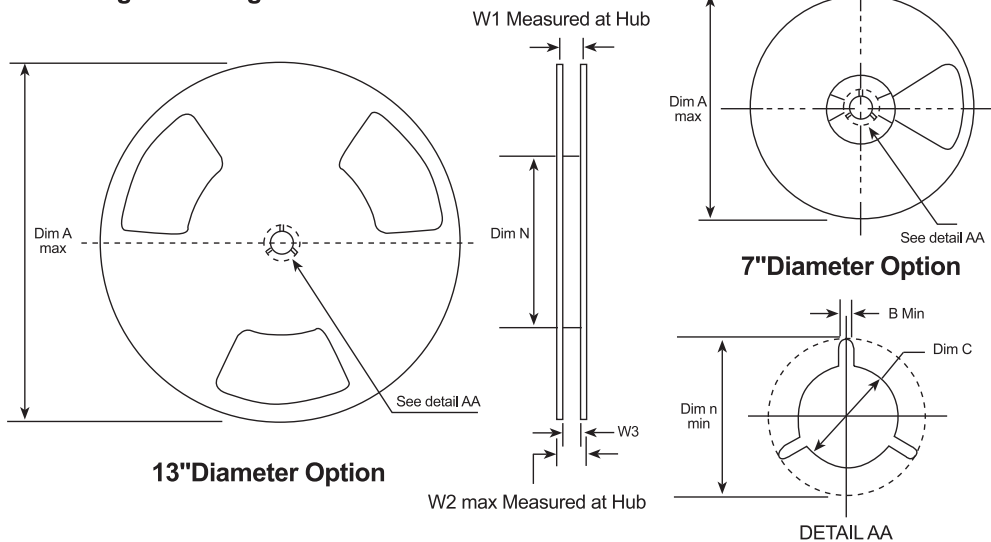
Dimensions are millimeter

Pkg type	A0	B0	W	D0	D1	E1	E2	F	P1	P0	K0	T	Wc	Tc
SOD323 (8mm)	1.46 +/-0.10	2.9 +/-0.10	8.0 +/-0.3	1.50 +/-0.125	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.10	4.0 +/-0.10	1.25 +/-0.10	0.25 +/-0.020	5.2 +/-0.20	0.06 +/-0.02

Notes: A0, B0 and K0 dimensions are determined with respect to the EW Jecdec RS-481 rotational and lateral movement requirements (see sketches A, B and C).



## SOD323 Reel Configuration: Figure 4.0



Dimensions are in inches and millimeter

Type Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512+0.020/-0.008 13+0.5/-0.2	0.795 20.0	2.165 55	0.331+0.059/-0.000 8.4+1.5/0	0.567 14.4	0.311-0.429 7.9-10.9
8mm	13" Dia	13.00 330	0.059 1.5	512+0.020/-0.008 13+0.5/-0.2	0.795 20.0	4.00 100	0.331+0.059/-0.000 8.4+1.5/0	0.567 14.4	0.311-0.429 7.9-10.9